

JFP PP7-3D



The machines which require minimal training to operate

- ▶ **Multi level Die Bonder**
- ▶ **Multiple height focusing**
- ▶ **Independent placement height**



The Model PP7 is designed to Place delicate devices on multi-level reference package.
PP7 achieves high accuracy placement using UHD optical device.

Programmable Vertical and co-axial Focusing camera make alignment references level, completely independent of bonding Heights.

Vision and placement are fully perpendicular to surface reference base of package.
Handling and centering is compatible with very delicate devices, as large I.R sensors, or MEMS...

A robust, and reliable mechanical concept, designed to be external vibration free.

Easy to use, flexible, the PP7 requires only minimum training to operate.

- **Programmable Focus = 20mm**
- **Orthogonal and Co-Axial Motions**
- **Related to reference base/Planarity**
- **Regular alignment reference points**
- **Circular Shape Alignment Reference**

DIE & SUBSTRATE

- Minimum die size 100*100µm
- Maximum die size 20*20 mm (more in option)
- Substrate handling, Up to 200x300 mm

VISION SYSTEM

- UHD Cameras, 5Mp or 18Mp
Powerful digital Zoom
- TFT monitor 17"
- LiED ghting, Oblic & Co-axial
- Direct placement
- 2 references points for auto-centering placement
- Indexed Pick& Place Positioning

XY TABLE

- Motorized X 260mm, Y 120mm
- Vibration free
- Motion control with progressive joystick

PARAMETERS & DISPLAY

- PC Interface, GUI Menu
- Programmable force 10gr to 700 gr
- Bond Force : 10g -700g , and up to 5 kg
- Programmable bond time
- Programmable scrub
- Indexed Pick and Placement mode
- Optional Flip Chip alignment, small & large dies
- Eutectic Chuck,+ gas environment
- Programmable ramp-up Temperature

Configurations

- Dispenser
- Stamping
- Customized work holder

Facilities

Power: 230VAC, 1 kva,
Vacuum : < 0,1 Bar
Dimensions : 650*820*1450mm
Weight : 110kg
Compressed Air : 6 bar